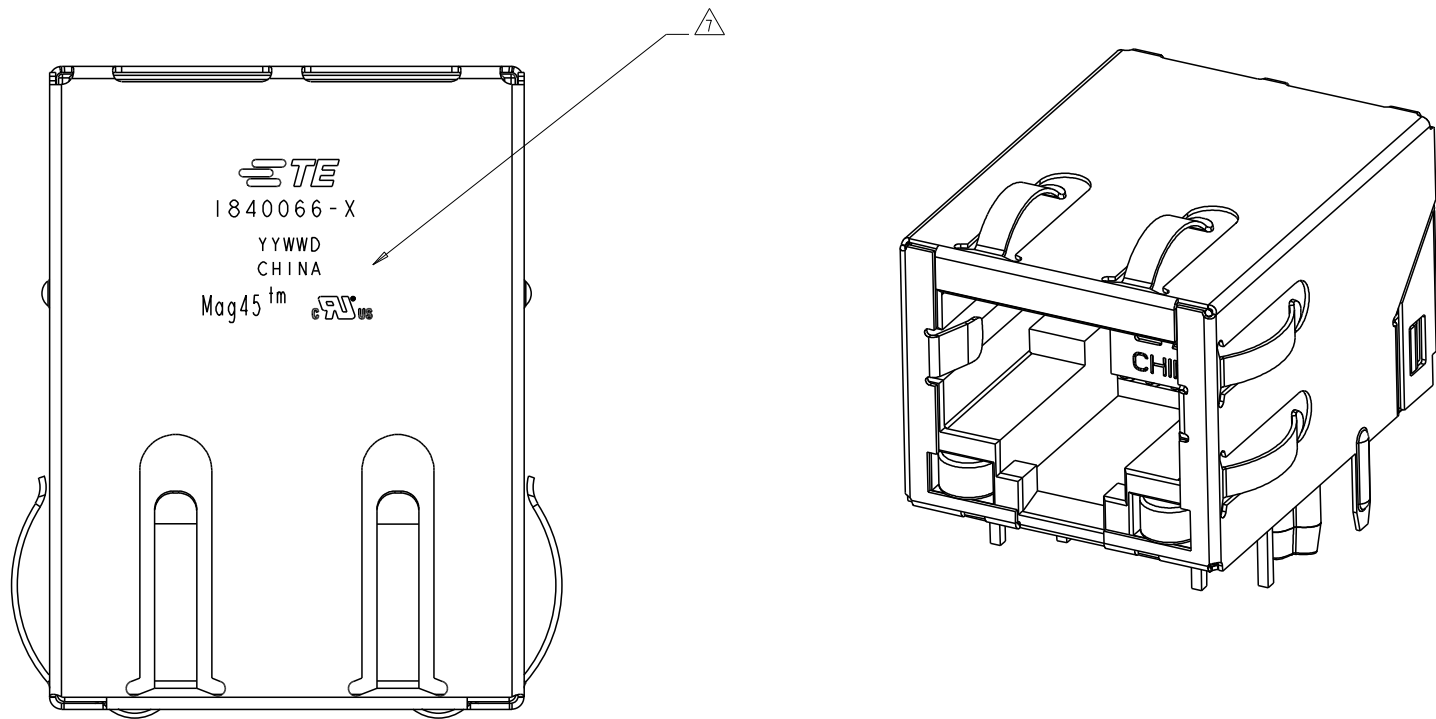


LOC	DIST	REVISIONS					
AA	00	P	LYR	DESCRIPTION	DATE	DWN	APVD
		1		INITIAL RELEASE	18JAN2012	RL	KZ
		2		SEE LAST SHEET	31JAN2012	TY	KZ
		A		ECO-12-008481	03MAY2012	RL	KZ

D



- 1 MATERIALS
- HOUSING: THERMOPLASTIC, FLAMMABILITY RATING UL 94V-0.
 - SHIELD: BRASS C26800 0.20mm THICK, PREPLATED WITH 0.76um MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 2.54um MIN SAC SOLDER.
 - CONTACTS: PHOSPHOR BRONZE 0.46mm X 0.30mm, PHOSPHOR BRONZE, 1.27um MIN NICKEL UNDERPLATE, WITH 1.27um MIN GOLD PLATING AT MATING INTERFACE AND 2.54um MIN MATTE TIN ON SOLDER TAILS, OR 1.27um MIN NICKEL UNDERPLATE, WITH 0.05um GOLD PLATING OVER 0.76um MIN PALLADIUM NICKEL PLATING AT MATING INTERFACE AND 2.54um MIN MATTE TIN ON SOLDER TAILS.
 - SOLDER TAILS: 0.25mmTHICK, PHOSPHOR BRONZE, 1.27um MIN OVERALL NICKEL UNDERPLATE, 3um TIN PLATE
 - LIGHT EMITTING DIODE (LED): DIFFUSED EPOXY LENS, 0.5mm X 0.5mm CARBON STEEL WIREFRAME LEADS PREPLATED WITH 2.03mm MIN. SILVER PLATE OVER 1.02mm MIN. NICKEL OVER 1.02mm MIN.COPPER UNDERPLATE; LEADS POST-PLATED WITH 3.05mm MIN. MATTE TIN.

- 2 RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 SUB PART F.

- 3 MAGNETICS
- APPLICATION: 10/100 BASE-T
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP:CABLE): TX = 1:1, RX = 1:1
 - OPEN CIRCUIT INDUCTANCE (OCL): 350uH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 - 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 - 12dB MIN FROM 60.1MHz TO 80MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 - 33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC

4. OPERATING TEMPERATURE: FROM 0°C TO 70°C.

- 5 INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.

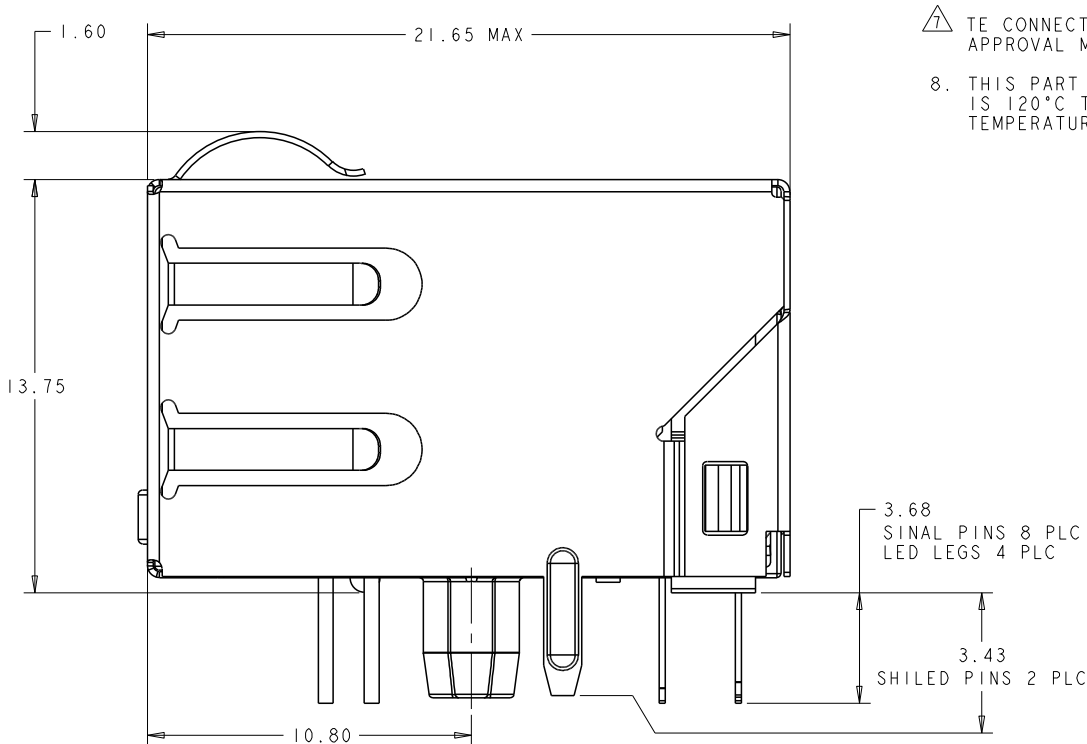
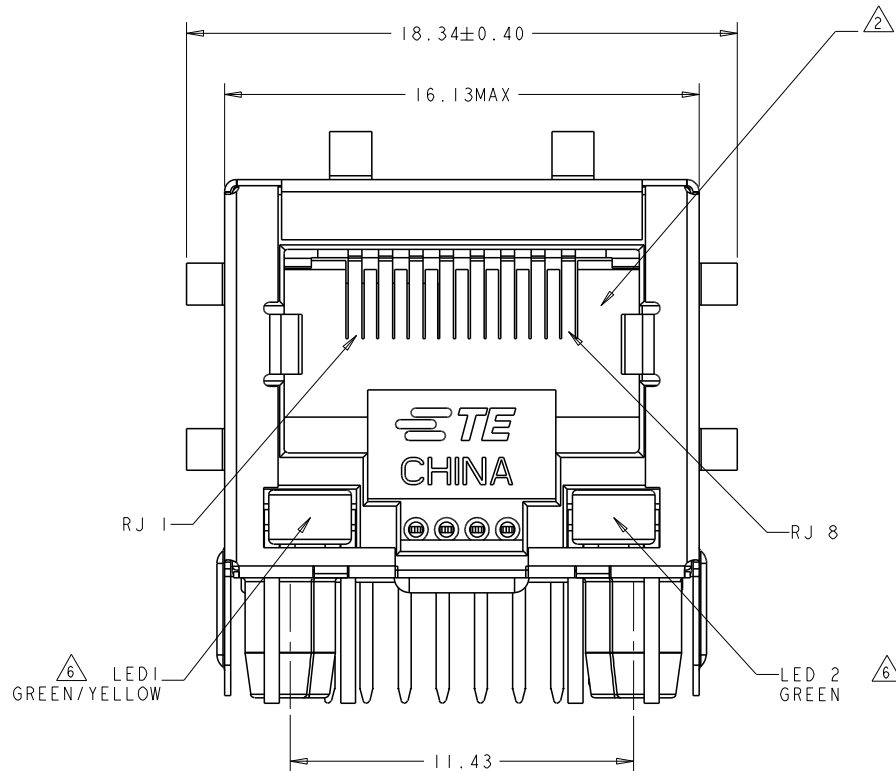
- 6 LEDS ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA
- LED COLOR: DOMINATE WAVELENGTH (λD): GREEN 568 nm TYP. AT IF = 20mA
FORWARD VOLTAGE (VF): GREEN 2.2V TYP. at IF = 20mA
DOMINATE WAVELENGTH (λD): YELLOW 588 nm TYP. AT IF = 20mA
FORWARD VOLTAGE (VF): YELLOW 2.1V TYP. at IF = 20mA

- 7 TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.


8. THIS PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS,PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX,10 SECONDS MAX.

C

B



1840066-5
PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN ROY LIU 18JAN2012		TE Connectivity	
DIMENSIONS:		CHK TOWER YU/FRANK LIU 18JAN2012		NAME	
mm		APPR KEITH ZHU 18JAN2012		IX1 MAG45(TM),MODULAR JACK, 32P13 10/100 CIRCUIT, SHIELDED AUTO-WELDING PROCESS, W/LD	
		PRODUCT SPEC 108-104004 APPLICATION SPEC		SIZE A1	
MATERIAL		WEIGHT		CAGE CODE 100779	
FINISH		SCALE		DRAWING NO C1840066	
CUSTOMER DRAWING		SHEET		RESTRICTED TO	
		OF		REV	

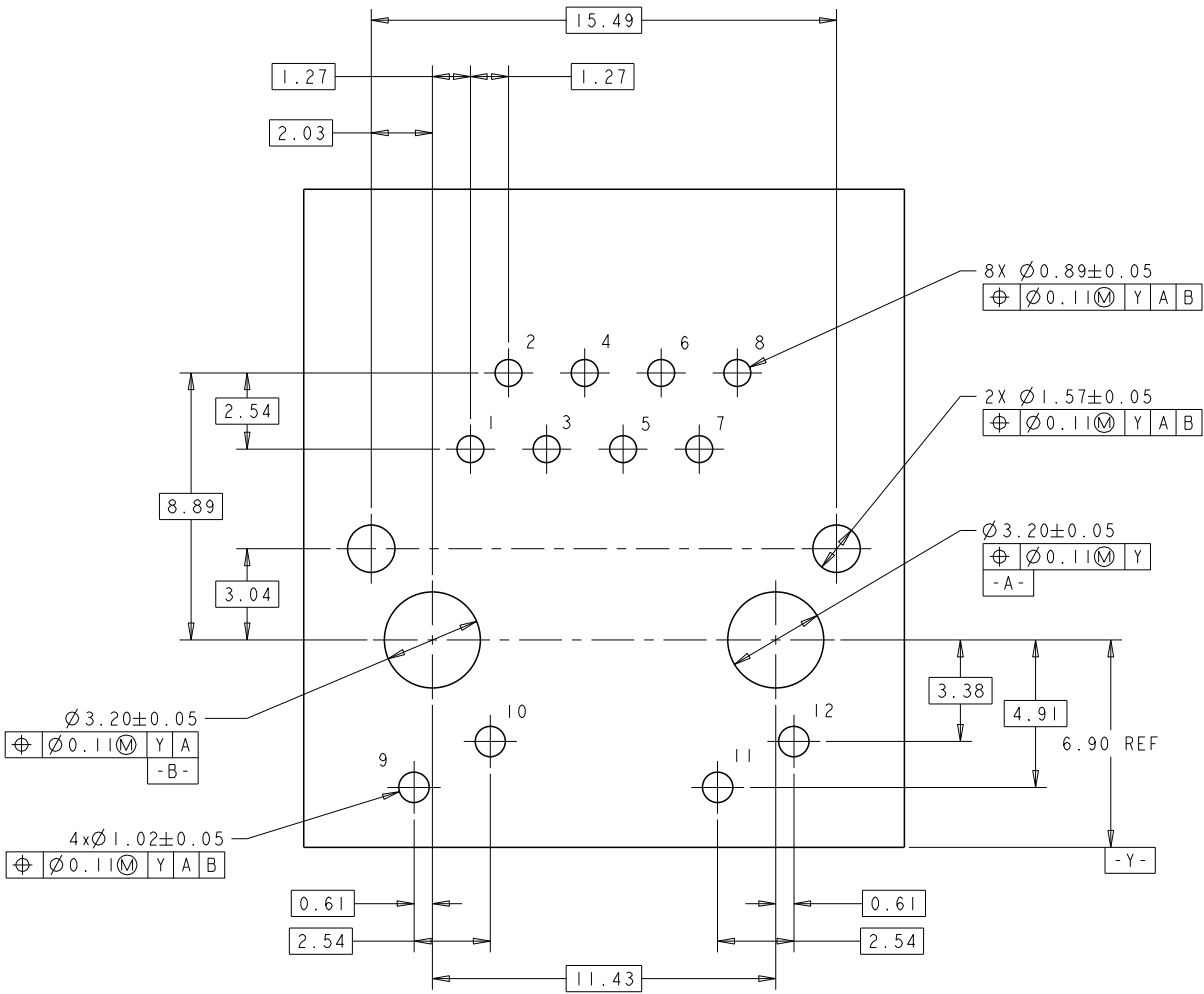
2		1					
LOC	DIST	REVISIONS					
AA	00	P	LTR	DESCRIPTION	DATE	DWN	APVD
			-	SEE SHEET 1	-	-	-

D

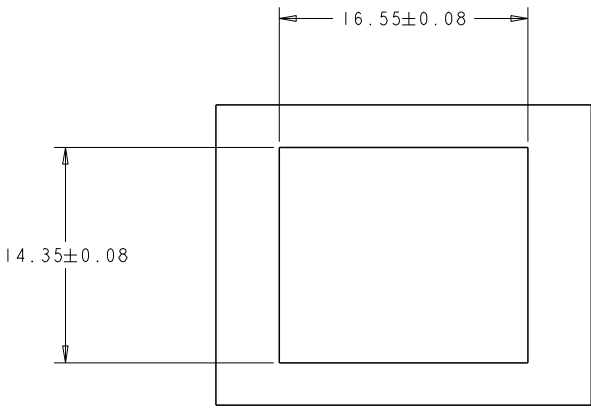
C

B

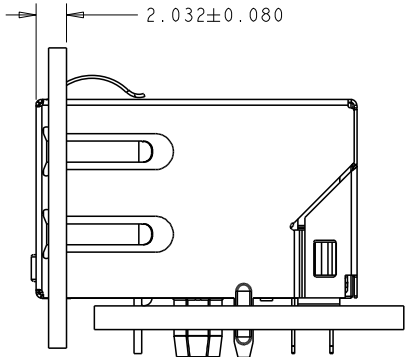
A



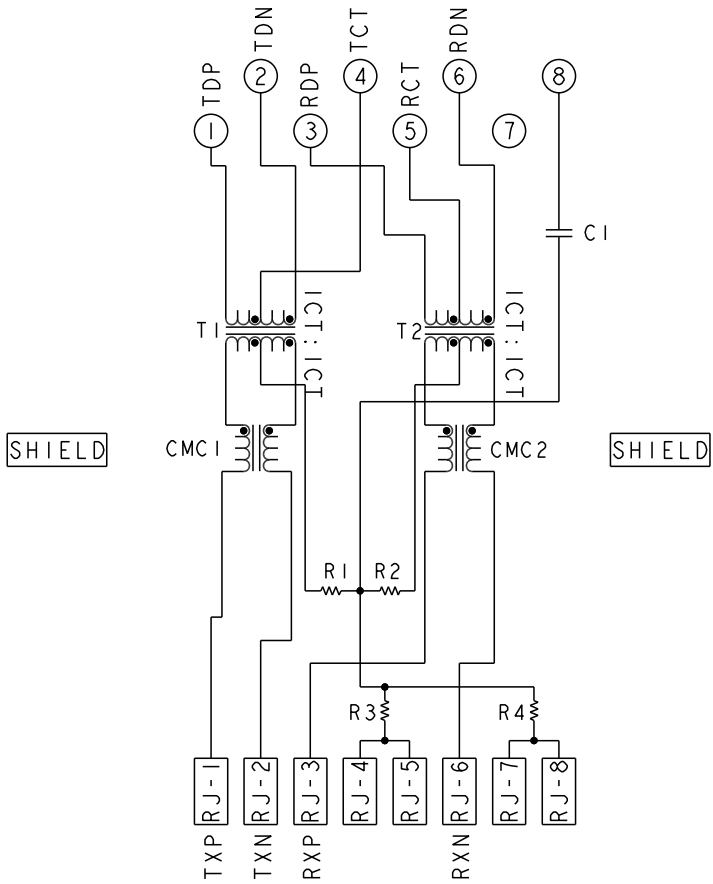
SUGGESTED PCB LAYOUT
COMPONENT SIDE



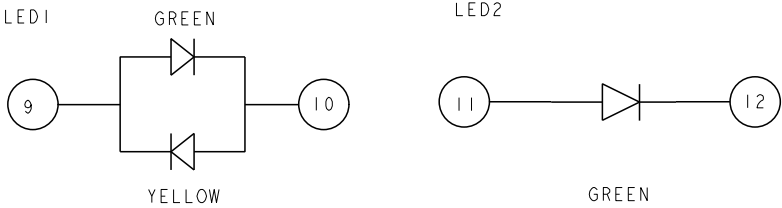
SUGGESTED PANEL CUTOUT
SCALE 4:1



326P13 10/100 BASE-T CIRCUIT $\triangle 3 \triangle 5$



C1=1000PF, 2kV, CAPACITOR
R1-R4=75 Ohms, RESISTORS



THIS DRAWING IS A CONTROLLED DOCUMENT.				OWN ROY LIU 18JAN2012				TE Connectivity			
DIMENSIONS:				CHK TOWER YU/FRANK LIU 18JAN2012				NAME			
mm				APRD KEITH ZHU 18JAN2012				PRODUCT SPEC			
								APPLICATION SPEC			
								RESTRICTED TO			
MATERIAL				FINISH				WEIGHT			
:				:				:			
								CUSTOMER DRAWING			
								SCALE 4:1			
								SHEET 2 OF 2			
								REV A			